# Plasma Etch of GaN using Panasonic Etcher

# **Experiment**

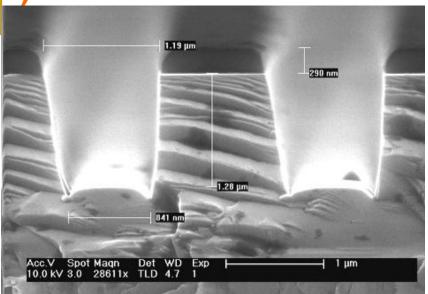
# **Material:**

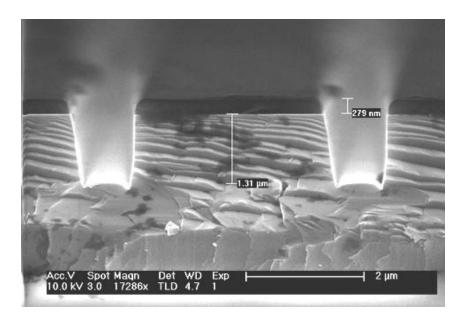
□Un-doped, GaN epitaxial layer (~2-µm in thickness) on a 2-inch sapphire substrate.

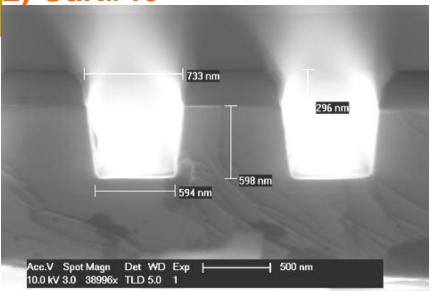
### **Methods:**

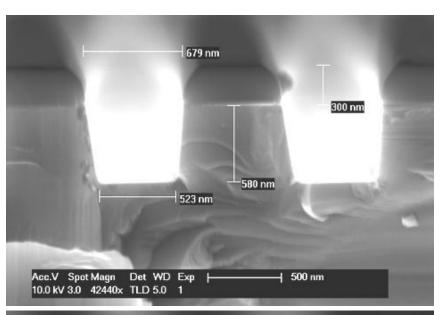
- □An 0.4-µm-thick SiO<sub>2</sub> layer grown on top of GaN using Unaxis ICP Deposition Tool at 250 °C.
- □Photo-resist ridge patterns, with different widths and separations, formed using stepper mask aligner.
- □Transferring the patterns into the SiO<sub>2</sub> layer using Panasonic ICP Etcher with CHF<sub>3</sub> chemistry.
- □Samples with a size of  $\sim 0.8 \times 0.8$  cm<sup>2</sup>, diced and etched using Panasonic ICP Etcher [Pre-etch native oxide removal:  $H_2SO_4$ : $H_2O_2$  (3:1), 1 minute].
- □Samples cleaved and examined by SEM.

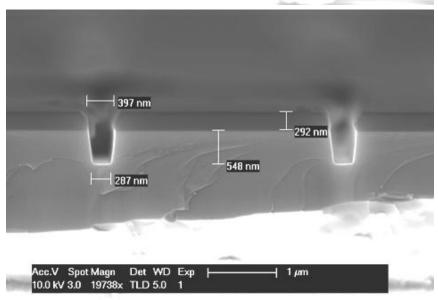
GaN Etch using Panasonic ICP Etcher @Room Temperature								
Sample #	Gas Flow Rate (sccm)		_					
	Cl <sub>2</sub>	$N_2$	Pressure (Pa)	Bias Power (W)	ICP Power (W)	Etch Rate (µm/min.)	Etch Selectivity (GaN/SiO <sub>2</sub> )	Side-wall Angle (°)
GaN#38	37.5	12.5	1.2	200	500	0.645	13.3	85.2
GaN#46	7	43	0.7	100	500	0.116	5.8	83.1
GaN#30	12.5	37.5	0.7	100	500	0.16	7.1	82.5
GaN#32	12.5	37.5	0.7	200	500	0.26	6.2	79.9
GaN#27	25	25	0.7	100	500	0.202	7.6	83.2
GaN#31	25	25	0.7	200	500	0.35	6.7	85.1
GaN#33	37.5	12.5	0.7	200	500	0.503	7.6	85.4
GaN#34	37.5	12.5	0.35	200	500	0.45	7.1	84.3
GaN#36	37.5	(BCl <sub>3</sub> =12.5)	0.35	200	500	0.48	7.9	86.9
GaN#35	50	0	0.35	200	500	0.432	5	82.8
GaN#43	22.5	(Ar=7.5)	0.3	200	500	0.504	4.6	80.3
GaN#40	22.5	7.5	0.2	100	500	0.268	14.3	84.7
GaN#37	22.5	7.5	0.2	200	500	0.336	5.5	86.2
GaN#41	22.5	7.5	0.2	200	900	0.345	6.7	85.8
GaN#42	22.5	7.5	0.2	300	500	0.605	6.2	86
GaN#39	30	0	0.2	200	500	0.44	5.8	83.8
GaN#47	11	33	0.2	50	900	0.0826	5.7	83.3
GaN#44	22.5	7.5	0.15	200	500	0.367	5.4	85.4
GaN#45	22.5	7.5	0.1	200	500	0.356	6.1	86.7
GaN#48	Cl <sub>2</sub> /BCl <sub>3</sub> /Ar:20/8/5		0.67	100	500	0.213	3.8	71.9

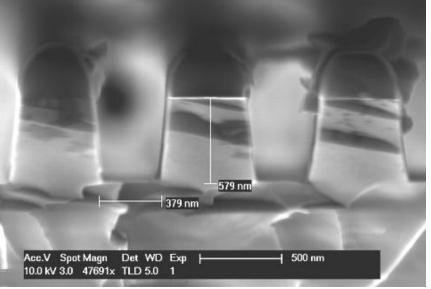


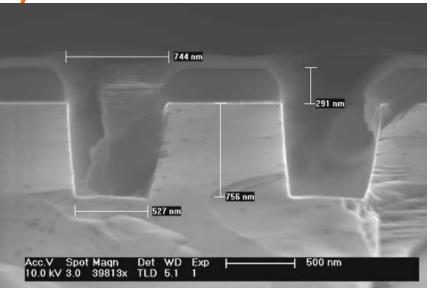


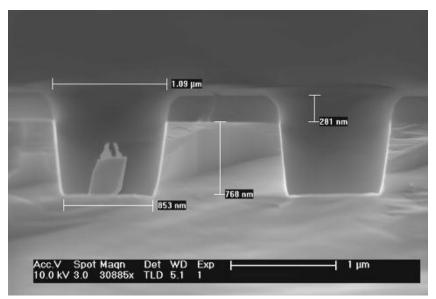


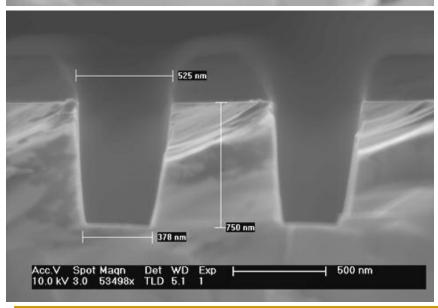


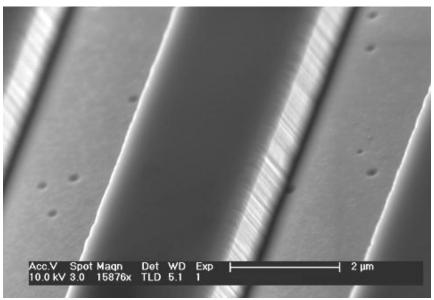




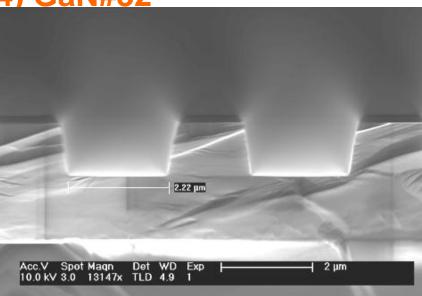


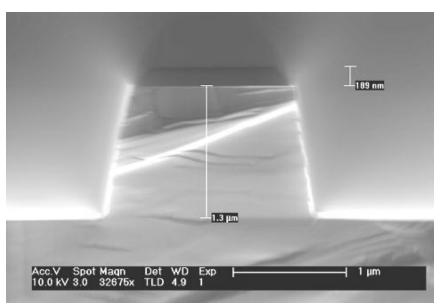


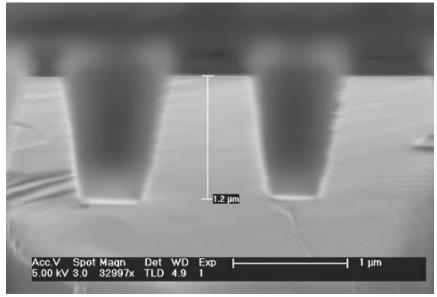




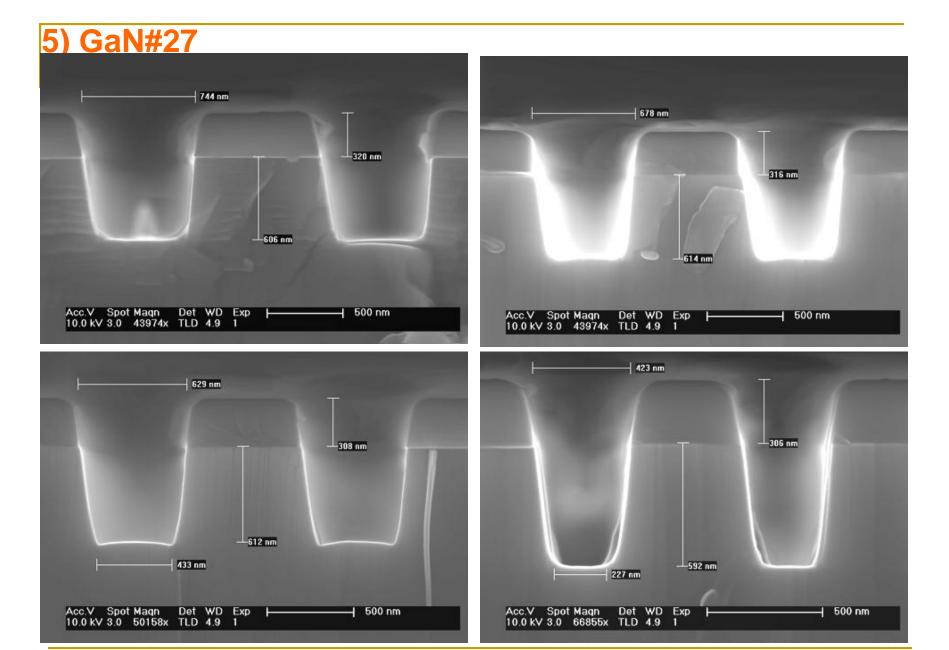
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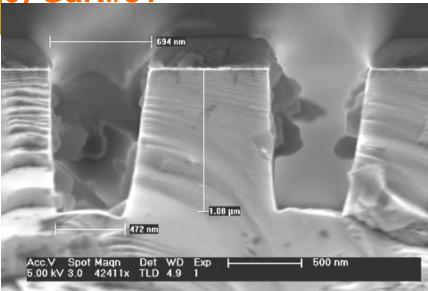


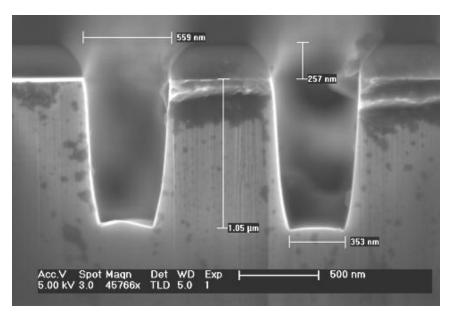


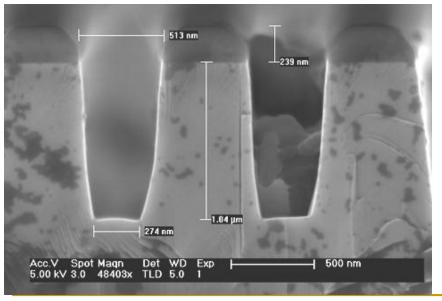


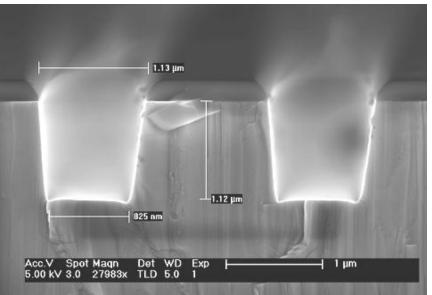
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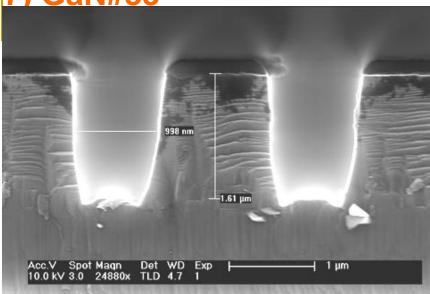


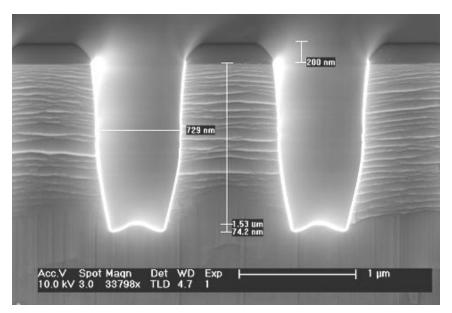


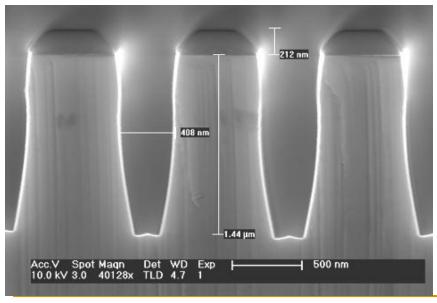


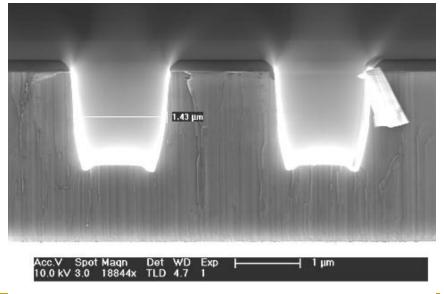


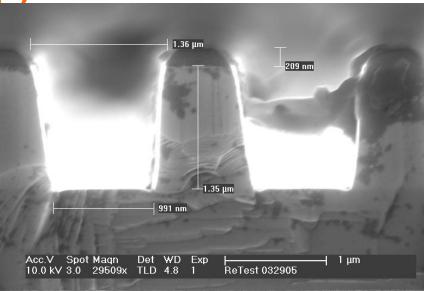
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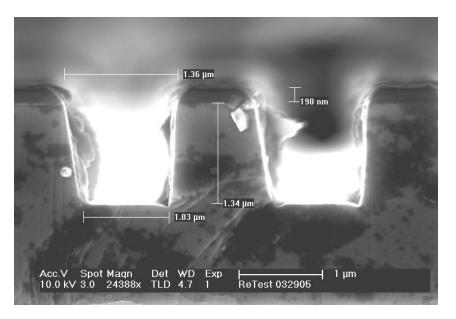


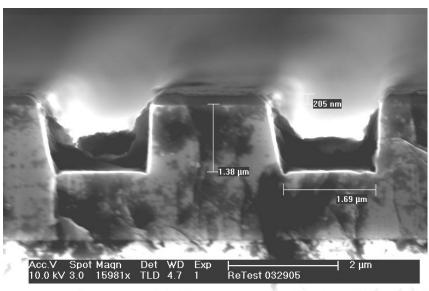




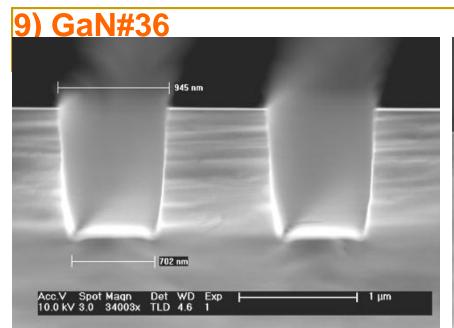


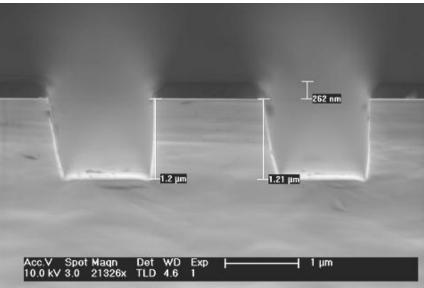


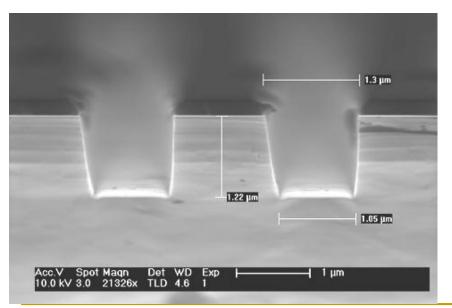


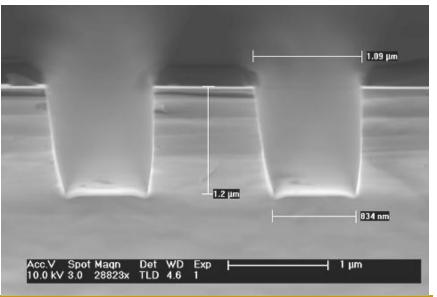




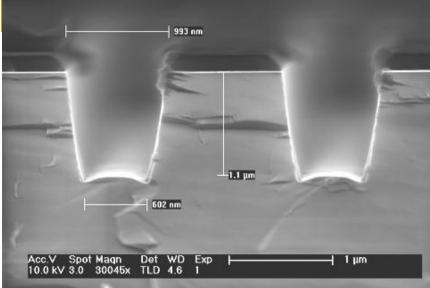


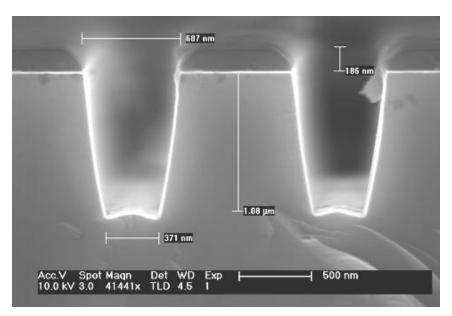


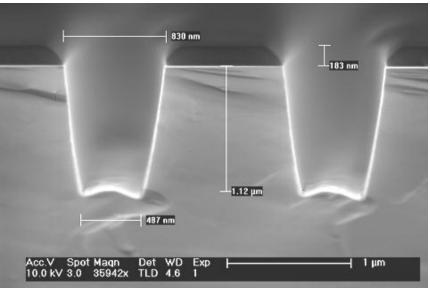


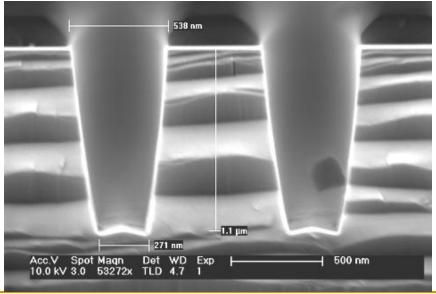


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# 11) GaN#43 1.01 µm 668 nm 136 nm 1.25 µm 253 nm 1.22 µm 509 nm Acc.V Spot Magn Det WD Exp |-5.00 kV 3.0 31522x TLD 5.0 1 Acc.V Spot Magn Det WD Exp |-5.00 kV 3.0 18592x TLD 5.0 1 1 μm - 1 2 μm 163 nm 709 nm 144 nm 1.28 µm 308 nm

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- 1 μm

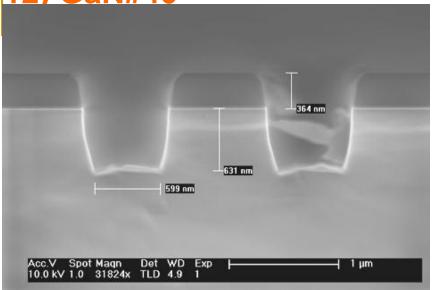
1.23 µm

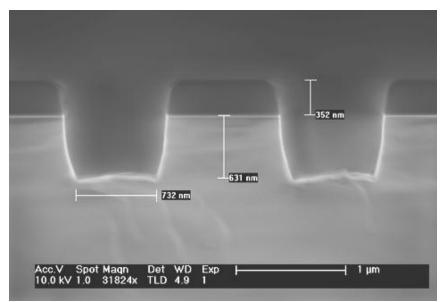
→ 500 nm

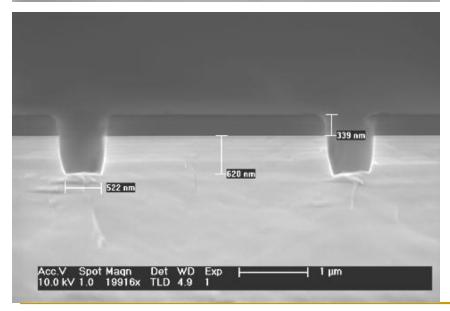
232 nm

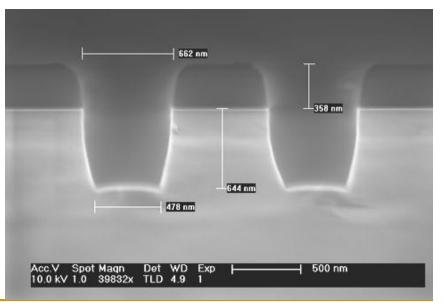
Acc.V Spot Magn Det WD Exp 5.00 kV 3.0 44130x TLD 5.0 1

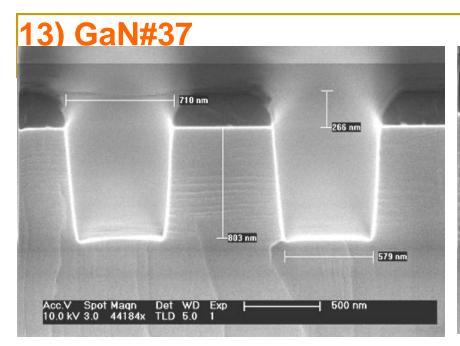
Acc.V Spot Magn Det WD Exp |-5.00 kV 3.0 30942x TLD 5.0 1

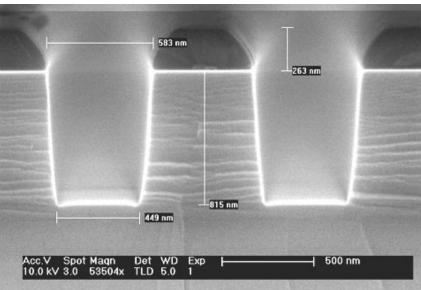


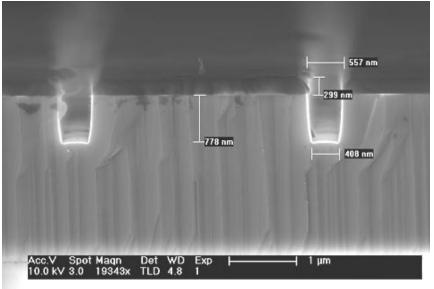


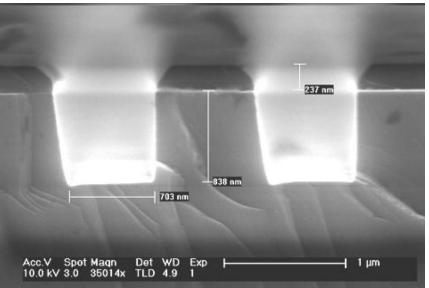






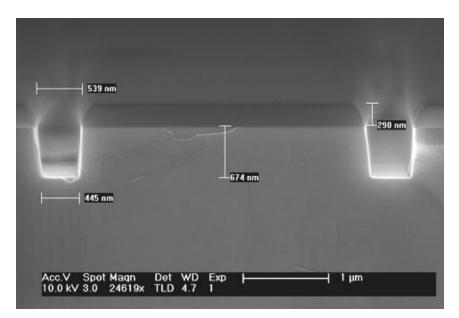


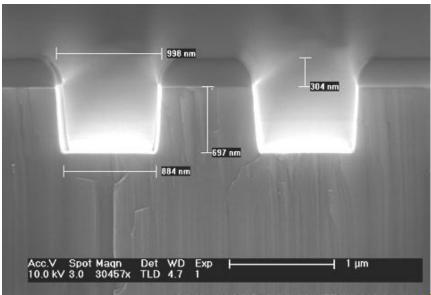


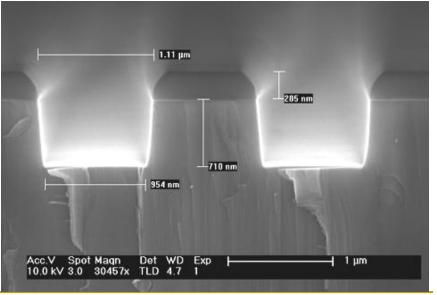


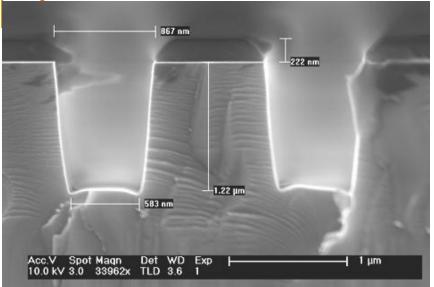
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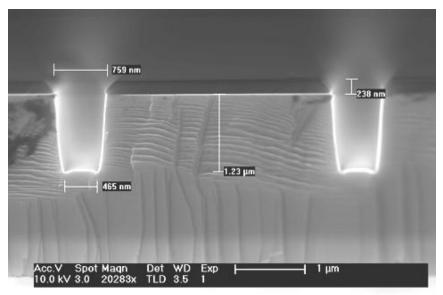


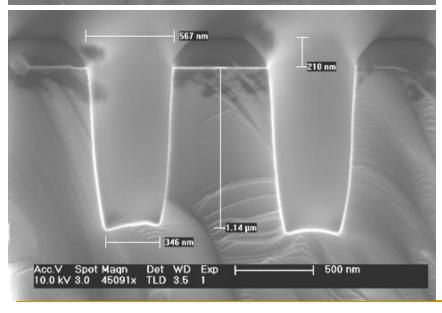


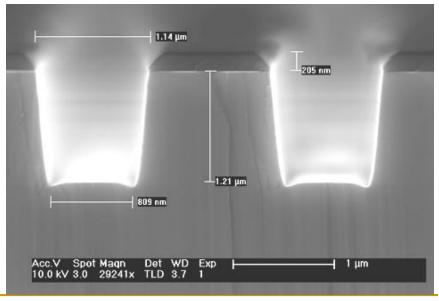


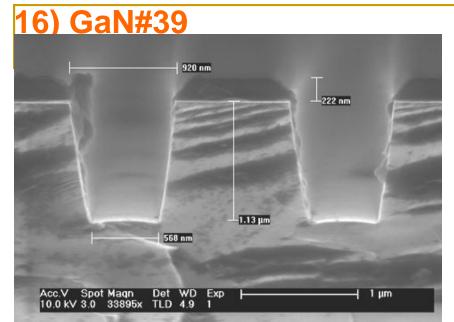


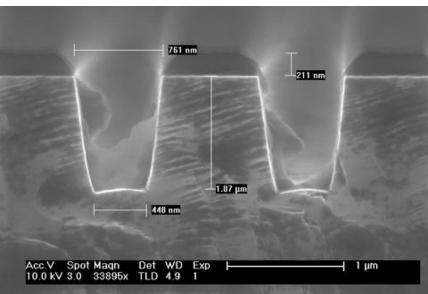


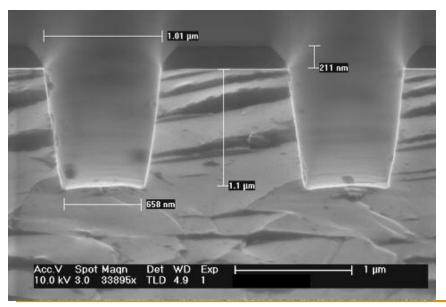


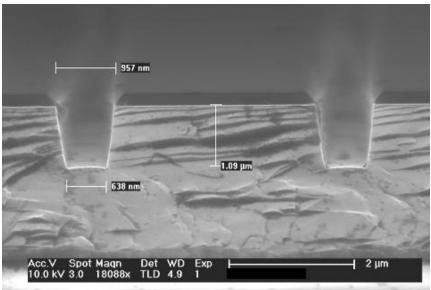


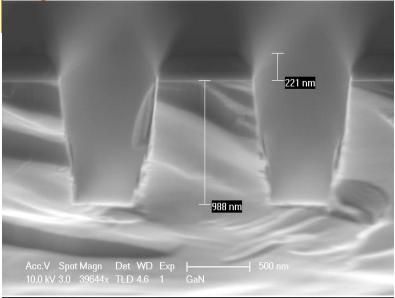


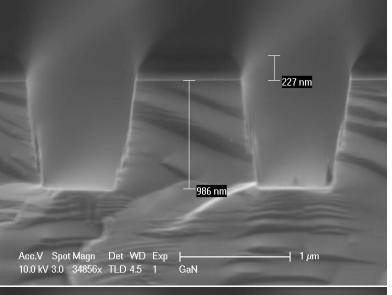


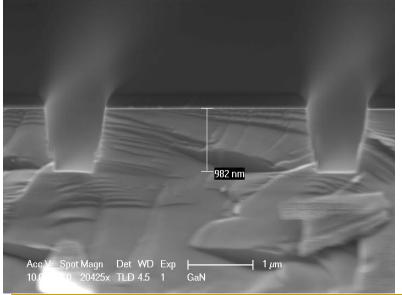


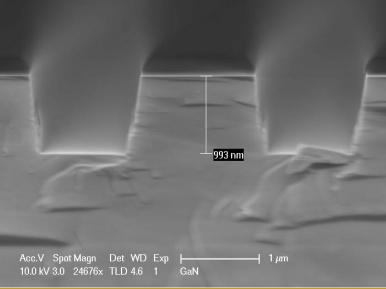




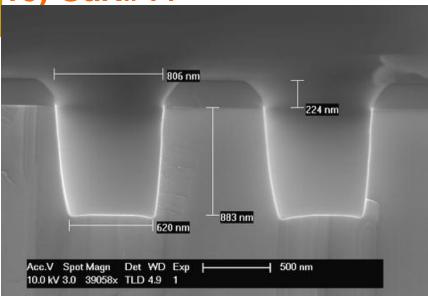


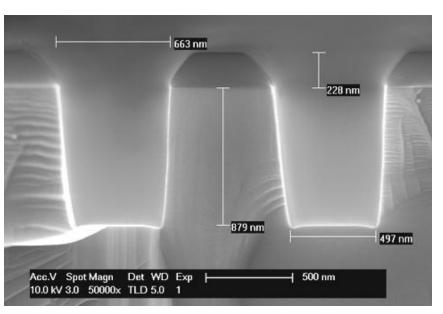


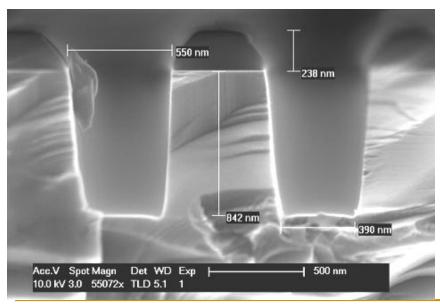


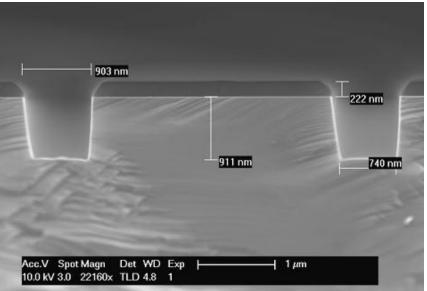


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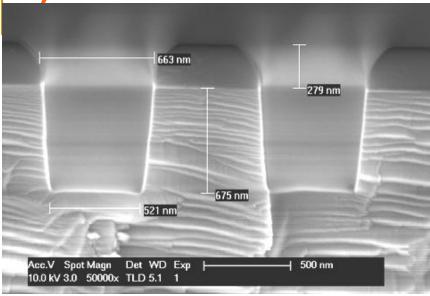


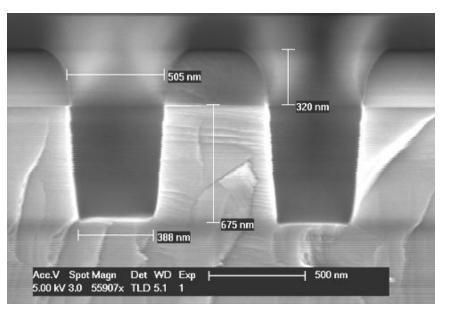


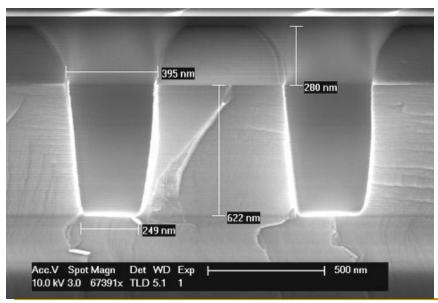


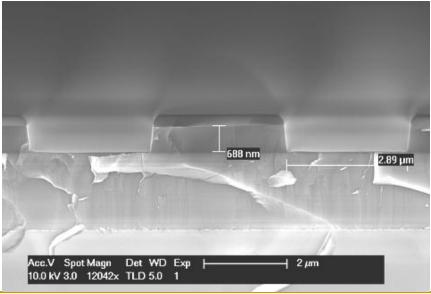


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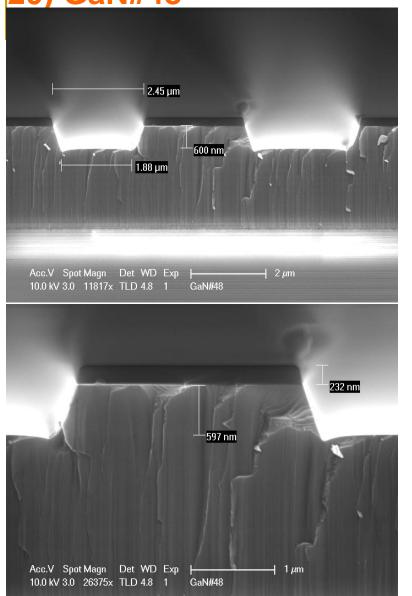


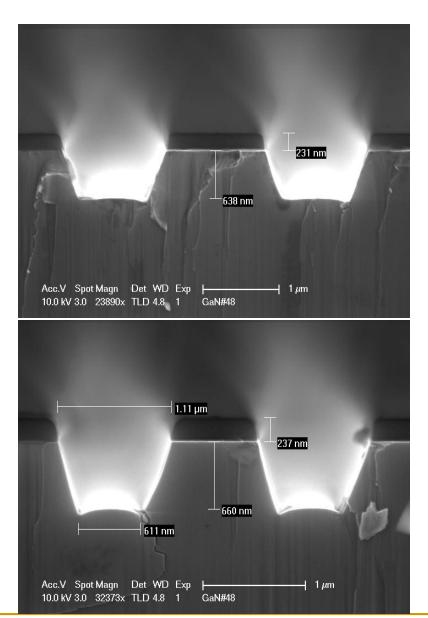






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